

November 1999 Revised March 2005

USB1T11A Universal Serial Bus Transceiver

General Description

The USB1T11A is a one chip generic USB transceiver. It is designed to allow 5.0V or 3.3V programmable and standard logic to interface with the physical layer of the Universal Serial Bus. It is capable of transmitting and receiving serial data at both full speed (12Mbit/s) and low speed (1.5Mbit/s) data rates.

The input and output signals of the USB1T11A conform with the "Serial Interface Engine". Implementation of the Serial Interface Engine along with the USB1T11A allows the designer to make USB compatible devices with off-the-shelf logic and easily modify and update the application.

Features

- Complies with Universal Serial Bus specification 1.1
- Utilizes digital inputs and outputs to transmit and receive USB cable data
- Supports 12Mbit/s "Full Speed" and 1.5Mbit/s "Low Speed" serial data transmission
- Compatible with the VHDL "Serial Interface Engine" from USB Implementers' Forum
- Supports single-ended data interface
- Single 3.3V supply
- ESD Performance: Human Body Model > 9.5 kV on D-, D+ pins only
 - > 4 kV on all other pins
- 16-lead Pb-Free MLP package saves space



Ordering Code:

Order Number	Package Number	Package Description
USB1T11AM (Note 1)	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
USB1T11AM_NL (Note 2)	M14A	Pb-Free 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
USB1T11ABQX	MLP16C	Pb-Free 16-Terminal Molded Leadless Package (MLP), JEDEC MO-220, 3mm square
USB1T11AMTC (Note 1)	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
USB1T11AMTC_NL (Note 2)	MTC14	Pb-Free 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
USB1T11AMTCX_NL (Note 2)	MTC14	Pb-Free 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Pb-Free package per JEDEC J-STD-020B.

Note 1: Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code.

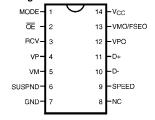
Note 2: "_NL" indicates Pb-Free package (per JEDEC J-STD-020B). Please use order number as indicated.

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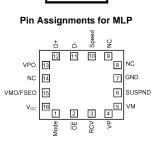


Connection Diagrams

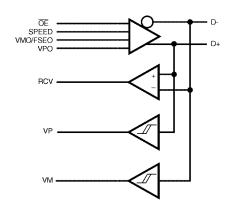
Pin Assignments for SOIC and TSSOP



Pin Assignments for MLP



Logic Diagram



Pin Descriptions

Pin Name	I/O			Description					
RCV	0	Receive data. CMOS	Receive data. CMOS level output for USB differential input						
ŌE	I		utput Enable. Active LOW, enables the transceiver to transmit data on the bus. When not ctive the transceiver is in receive mode.						
MODE	I	Mode. When left unco VMO/FSEO pin takes		oull-up transistor pulls it to EO (Force SEO).	V _{CC} and in this GND, the				
V _{PO} , V _{MO} /F _{SEO}	ı	Inputs to differential di	river. (Outputs fron	n SIE).					
		MODE	VPO	VMO/FSEO	RESULT				
		0	0	0	Logic "0"				
			0	1	SE0				
			1	0	Logic "1"				
			1	1	SEO				
		1	0	0	SE0				
			0	1	Logic "0"				
			1	0	Logic "1"				
			1	1	Illegal code				
V_P, V_M	0	Gated version of D- and D+. Outputs are logic "0" and logic "1". Used to detect single end zero (SE0), error conditions, and interconnect speed. (Input to SIE).							
		VP	VM	RESULT					
		0	0	SE0					
		0	1	Low Speed					
		1	0	Full Speed					
		1	1	Error					
D+, D-	AI/O	Data+, Data Differer	ntial data bus confo	orming to the Universal Se	rial Bus standard.				
SUSPND	I			ile the USB bus is inactive "0" state. Both D+ and D–	e. While the suspend pin is are 3-STATE.				
SPEED	I	Edge rate control. Log Logic "0" operates edge		edge rates for "full speed". beed".					
V _{CC}		3.0V to 3.6V power su	ipply						
GND		Ground reference							

Functional Truth Table

	Input				I/O			Outputs		
Mode	VPO	VMO/FSEO	OE	SUSPND	D+	D-	RCV	V _P	V _M	Result
0	0	0	0	0	0	1	0	0	1	Logic 0
0	0	1	0	0	0	0	U	0	0	SEO
0	1	0	0	0	1	0	1	1	0	Logic 1
0	1	1	0	0	0	0	U	0	0	SEO
1	0	0	0	0	0	0	U	0	0	SEO
1	0	1	0	0	0	1	0	0	1	Logic 0
1	1	0	0	0	1	0	1	1	0	Logic 1
1	1	1	0	0	1	1	U	U	U	Illegal Code
Х	Х	X	1	0	Z	Z	U	U	U	D+/D- Hi-Z
Х	Х	Х	1	1	Z	Z	U	U	U	D+/D- Hi-Z

X = Don't Care
Z = 3-STATE
U = Undefined State

Absolute Maximum Ratings(Note 3)

DC Supply Voltage (V_{CC}) -0.5V to +7.0V

DC Input Diode Current (I_{IK})

 $V_I < 0$ –50 mA

Input Voltage (V_I)

(Note 4) -0.5V to +5.5V

Input Voltage ($V_{I/O}$) -0.5V to V_{CC} + 0.5V

Output Diode Current (I_{OK})

 $V_O > V_{CC}$ or $V_O < 0$ ±50 mA

Output Voltage (V_O)

(Note 4) -0.5V to $V_{CC} + 0.5V$

Output Source or Sink Current (IO)

VP.VM, RCV pins

 $V_O = 0 \text{ to } V_{CC}$ ±15 mA

Output Source or Sink Current (IO)

D+/D- pins

 V_O = 0 to V_{CC} ± 50 mA

 V_{CC} or GND Current (I_{CC} , I_{GND}) ±100 mA

Storage Temperature (T_{STO}) -60°C to + 150°C

Recommended Operating Conditions

Supply Voltage V_{CC} 3.0V to 3.6V

Input Voltage (V_I) 0V to 5.5V

 $\begin{array}{ll} \text{Input Range for AI/O (V}_{\text{AI/O}}) & \text{OV to V}_{\text{CC}} \\ \text{Output Voltage (V}_{\text{O}}) & \text{OV to V}_{\text{CC}} \\ \end{array}$

Operating Ambient Temperature

in free air (T_{amb}) $-40^{\circ}C$ to $+85^{\circ}C$

Note 3: The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristic tables are not guaranteed at the absolute maximum rating. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Note 4: The input and output voltage ratings may be exceeded if the input and output clamp current ratings are observed.

and output damp durient ratings are

DC Electrical Characteristics (Digital Pins)

Over recommended range of supply voltage and operating free air temperature (unless otherwise noted). $V_{CC} = 3.0V$ to 3.6V

				Limits			
Symbol	Parameter	Test Conditions	Temp	Unit			
			Min	Тур	Max		
	INPUT LEVELS:	•				•	
V _{IL}	LOW Level Input Voltage				0.8	V	
V _{IH}	HIGH Level Input Voltage		2.0			V	
	OUTPUT LEVELS:	•				•	
V _{OL}	LOW Level Output Voltage	I _{OL} = 4 mA			0.4	V	
		$I_{OL} = 20 \mu A$			0.1	_ v	
V _{OH}	HIGH Level Output Voltage	I _{OH} = 4 mA	2.4			V	
		$I_{OH} = 20 \mu A$	V _{CC} - 0.1			_ v	
	LEAKAGE CURRENT:	•				•	
IL	Input Leakage Current	V _{CC} = 3.0 to 3.6			±5	μΑ	
I _{CCFS}	Supply Current (Full Speed)	V _{CC} = 3.0 to 3.6			5	mA	
I _{CCLS}	Supply Current (Low Speed)	V _{CC} = 3.0 to 3.6			5	mA	
I _{CCQ}	Quiescent Current	V _{CC} = 3.0 to 3.6			5	mA	
		$V_{IN} = V_{CC}$ or GND			3	IIIA	
I _{CCS}	Supply Current in Suspend	V _{CC} = 3.0 to 3.6; Mode = V _{CC}			10	μА	

DC Electrical Characteristics (D+/D- Pins)

Over recommended range of supply voltage and operating free air temperature (unless otherwise noted). $V_{CC} = 3.0 \text{V}$ to 3.6 V

				Units		
Symbol	Parameter	Test Conditions	Temp			
			Min	Тур	Max	1
	INPUT LEVELS:					
V _{DI}	Differential Input Sensitivity	(D+) - (D-)	0.2			V
V _{CM}	Differential Common Mode Range	Includes V _{DI} Range	0.8		2.5	V
V _{SE}	Single Ended Receiver Threshold		0.8		2.0	V
	OUTPUT LEVELS:					
V _{OL}	Static Output LOW Voltage	R_L of 1.5 k Ω to 3.6V			0.3	V
V _{OH}	Static Output HIGH Voltage	R_L of 15 k Ω to GND	2.8		3.6	V
V _{CR}	Differential Crossover		1.3		2.0	V
	LEAKAGE CURRENT:		•	•		
I _{OZ}	High Z State Data Line Leakage Current	0V < V _{IN} < 3.3V			±5	μА
	CAPACITANCE:					
C _{IN} (Note 6)	Transceiver Capacitance	Pin to GND			10	pF
	Capacitance Match				10	%
	OUTPUT RESISTANCE:		· · · · · · · · · · · · · · · · · · ·	ı		
Z _{DRV} (Note 5)	Driver Output Resistance	Steady State Drive	4		20	Ω
	Resistance Match				10	%
Mata E. Fredric	des suternal register. In order to comply with	HOD Oifti 4.4tli		40/	D 10	

Note 5: Excludes external resistor. In order to comply with USB Specification 1.1, external series resistors of 24Ω ± 1% each on D+ and D- are recommended. This specification is guaranteed by design and statistical process distribution.

Note 6: This specification is guaranteed by design and statistical process distribution.

AC Electrical Characteristics (D+/D- Pins, Full Speed)

Over recommended range of supply voltage and operating free air temperature (unless otherwise noted). $V_{CC}=3.0V$ to 3.6V C_L = 50 pF; R_L = 1.5 k Ω on D+ to V_{CC}

			Limits Temp = -40°C to +85°C				
Symbol	Parameter	Test Condition	Temp	Units			
			Min	Тур	Max	1	
	DRIVER CHARACTERISTICS:	•	•			ı	
		10% and 90%				ns	
t_R	Rise Time	Figure 1	4		20		
t_{F}	Fall Time	Figure 1	4		20		
t _{RFM}	Rise/Fall Time Matching	(t_r/t_f)	90		110	%	
V _{CRS}	Output Signal Crossover Voltage		1.3		2.0	V	
	DRIVER TIMINGS:		•			•	
t _{PLH}	Driver Propagation Delay	Figure 2			18	ns	
t _{PLH}	(VPO, VMO/FSEO to D+/D-)	Figure 2			18	ns	
t _{PHZ}	Driver Disable Delay	Figure 4			13	ns	
t _{PLZ}	(OE to D+/D-)	Figure 4			13	ns	
t _{PZH}	Driver Enable Delay	Figure 4			17	ns	
t _{PZL}	(OE to D+/D-)	Figure 4			17	ns	
	RECEIVER TIMINGS:	·					
t _{PLH}	Receiver Propagation Delay	Figure 3			16	ns	
t _{PHL}	(D+, D- to RCV)	Figure 3			19	ns	
t _{PLH}	Single-ended Receiver Delay	Figure 3			8	ns	
t _{PHL}	(D+, D- to VP, VM)	Figure 3			8	ns	

AC Electrical Characteristics (D+/D- Pins, Low Speed)

Over recommended range of supply voltage and operating free air temperature (unless otherwise noted). V_{CC} = 3.0V to 3.6V C_L = 200 pF to 600 pF; R_L = 1.5k Ω on D– to V_{CC}

			Limits			
Symbol	Parameter	Test Conditions	Tan	Unit		
			Min	Тур	Max	
	DRIVER CHARACTERISTICS:		•		•	
		10% and 90%				
t_{LR}	Rise Time	Figure 1	75		300	ns
t _{LF}	Fall Time	Figure 1	75		300	
t _{RFM}	Rise/Fall Time Matching	(t_r/t_f)	80		120	%
V _{CRS}	Output Signal Crossover Voltage		1.3		2.0	V
	DRIVER TIMINGS:	•				
t _{PLH}	Driver Propagation Delay	Figure 2			300	ns
t _{PHL}	(VPO, VMO/FSEO to D+/D-)	Figure 2			300	ns
t _{PHZ}	Driver Disable Delay	Figure 4			13	ns
t _{PLZ}	(OE to D+/D-)	Figure 4			13	ns
t _{PZH}	Driver Enable Delay	Figure 4			205	ns
t _{PZL}	(OE to D+/D-)	Figure 4			205	ns
	RECEIVER TIMINGS:		•			•
t _{PLH}	Receiver Propagation Delay	Figure 3			18	ns
t _{PHL}	(D+, D- to RCV)	Figure 3			18	ns
t _{PLH}	Single-ended Receiver Delay	Figure 3			28	ns
t _{PHL}	(D+, D- to VP, VM)	Figure 3			28	ns

AC Waveforms

 V_{OL} and V_{OH} are the typical output voltage drops that occur with the output load. (V_{CC} never goes below 3.0V)

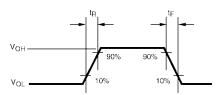


FIGURE 1. Rise and Fall Times

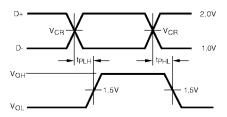


FIGURE 2. VPI, VMO/FSEO to D+/D-

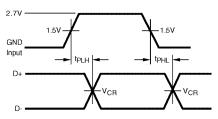


FIGURE 3. D+/D- to RCV, VP/VM

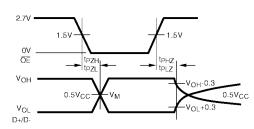
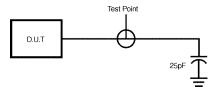
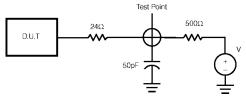


FIGURE 4. OE to D+/D-

Test Circuits and Waveforms



Load for VM/VP and RCV

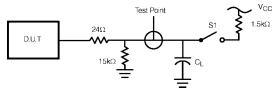


Load for Enable and Disable Times

Note:

 $V=0 \ for \ t_{PZH}, \ t_{PHZ}$

 $V = \, V_{CC} \, for \, \, t_{PZL}, \, \, t_{PLZ}$



Load for D+/D-

 C_L = 50 pF, Full Speed

 $C_L = 200 \text{ pF, Low Speed (Min Timing)}$

 $C_L = 600 \text{ pF}$, Low Speed (Max Timing)

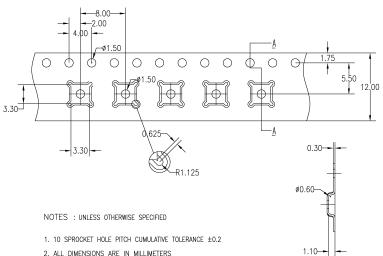
1.5 k Ω on D– (Low Speed) or D+ (Full Speed) only

Test	S1
D-/LS	Close
D+/LS	Open
D-/FS	Open
D+/FS	Close

Tape and Reel Specification Tape Format for MLP

Tape Formation ML	F			
Package	Tape	Number	Cavity	Cover Tape
Designator	Section	Cavities	Status	Status
	Leader (Start End)	125 (typ)	Empty	Sealed
BQX	Carrier	2500	Filled	Sealed
	Trailer (Hub End)	75 (typ)	Empty	Sealed

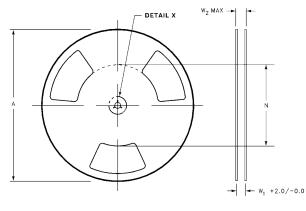
TAPE DIMENSIONS inches (millimeters)

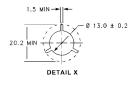


- 2. ALL DIMENSIONS ARE IN MILLIMETERS
- 3. POCKET POSITION RELATIVE TO SPROCKET HOLE MEASURED AS TRUE POSITION OF POCKET, NOT POCKET HOLE
- 4. CAMBER IN COMPLIANCE WITH EIA 481
- 5. ADVANTEK PART DRAWING NUMBER ML0303-A

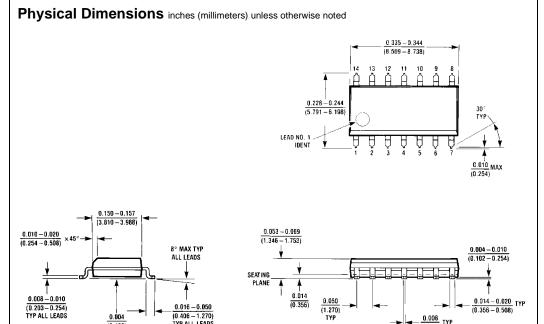
<u>SECTION A - A</u>

REEL DIMENSIONS inches (millimeters)





Tape Size	A (mm)	N (Typical) (mm)	W1 (mm)	W2 (Max) (mm)
12 mm	330	178	12.4	18.4



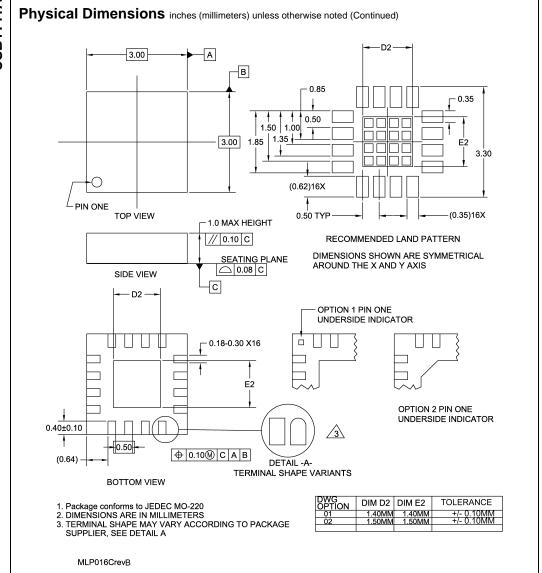
14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow Package Number M14A

0.016 - 0.050 (0.406 - 1.270) TYP ALL LEADS

0.004 (0.102) ALL LEAD TIPS

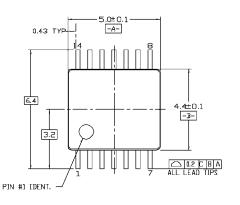
- (0.00B) TYP

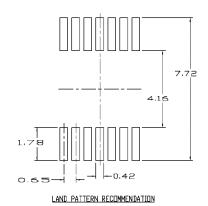
M14A (REV H)

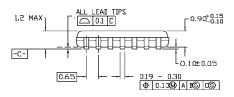


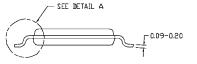
Pb-Free 16-Terminal Molded Leadless Package (MLP), JEDEC MO-220, 3mm square Package Number MLP16C

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)





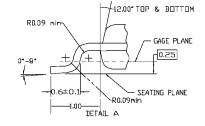




NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB., REF NOTE 6, DATED 7/93
- B. DIMENSIONS ARE IN MILLIMETERS
- C. DIMENSIONS ARE EXCLUSIVE DF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
 D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1982

MTC14revD



14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC14

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